

ABSTRACT OF THE DISCLOSURE

Provided is a semiconductor sealing material in which the contamination rate of conductive foreign matter is extremely low. Further provided are powder comprising spherical silica powder and/or spherical alumina powder suitable for preparing such a semiconductor sealing material, a method for producing the same, and a resin composition. The powder comprises spherical silica powder and/or spherical alumina powder, and when a color reaction test for particles using an aqueous potassium ferricyanide solution under specific conditions is performed for magnetizable particles having a particle size of 45 μm or more, the ratio of the number of particles which develop color to the total number of the magnetizable particles is 20% or less. Such powder can be produced by supplying a specific amount of oxygen gas and/or water vapor to at least one arbitrary site at which the atmospheric temperature is 1600 to 1800 DEG C in a furnace at an angle of 60 DEG to 90 DEG with respect to the injection direction of a starting material of the powder, and setting the relative velocity of the starting material of the powder and/or the spherical powder to stainless steel and/or iron to 5 m/s or less.